



HSC3417

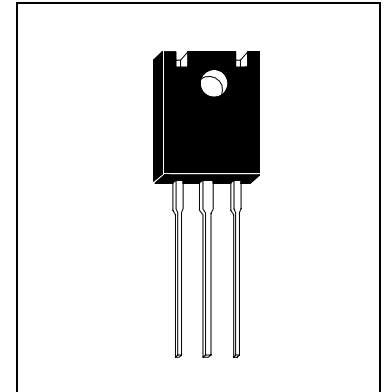
NPN EPITAXIAL PLANAR TRANSISTOR

Features

- High-Definition CRT Display Video Output Applications
- High Breakdown Voltage: BVCEO=300V

Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
 Storage Temperature -50 ~ +150 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 1.2 W
 Total Power Dissipation (Tc=25°C) 7 W
- Maximum Voltages and Currents
 BVCBO Collector to Base Voltage 300 V
 BVCEO Collector to Emitter Voltage 300 V
 BVEBO Emitter to Base Voltage 5 V
 IC Collector Current 100 mA



Electrical Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	300	-	-	V	IC=100uA
BVCEO	300	-	-	V	IC=1mA
BVEBO	5	-	-	V	IE=10uA
ICBO	-	-	100	nA	VCB=200V
IEBO	-	-	100	nA	VEB=4V
*VCE(sat)	-	-	600	mV	IC=20mA, IB=2mA
*VBE(sat)	-	-	1	V	IC=20mA, IB=2mA
*hFE	40	-	320		IC=10mA, VCE=10V
fT	-	70	-	MHz	IC=10mA, VCE=30V, f=100MHz
Cob	-	2.6	-	pF	VCB=30V, f=1MHz

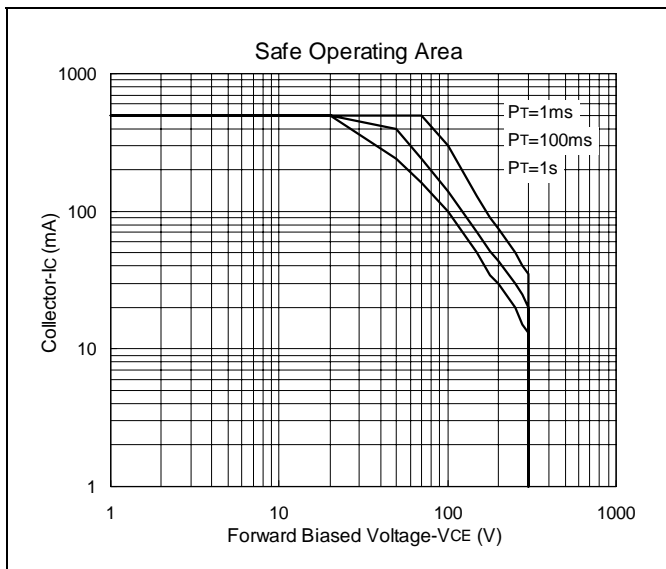
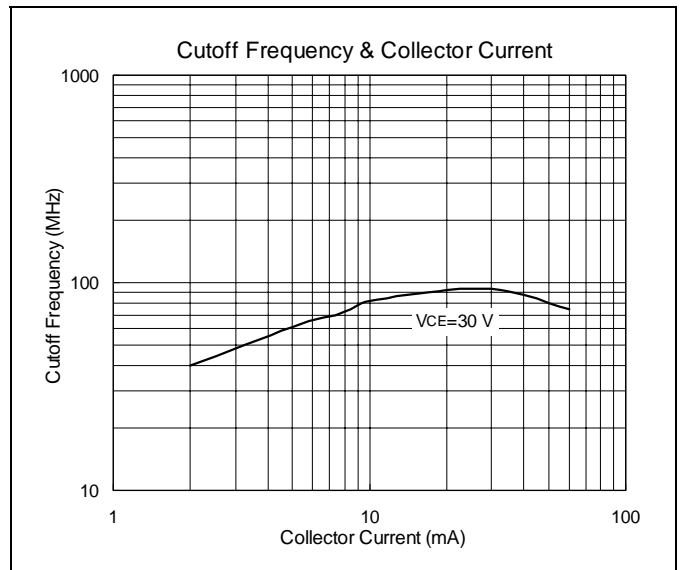
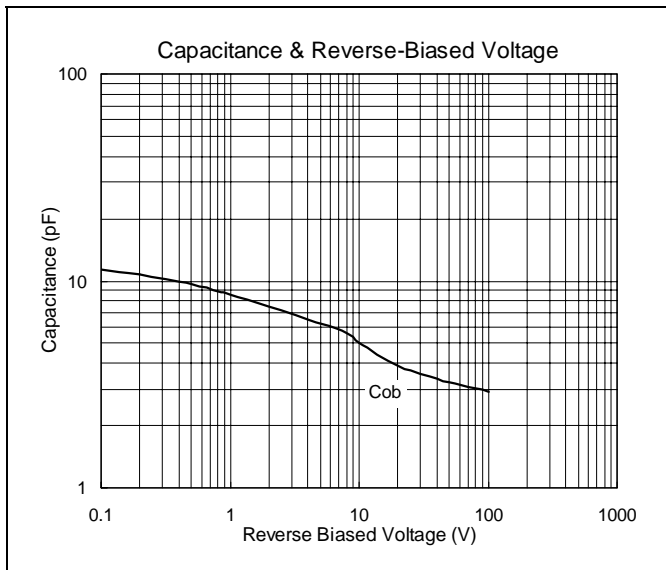
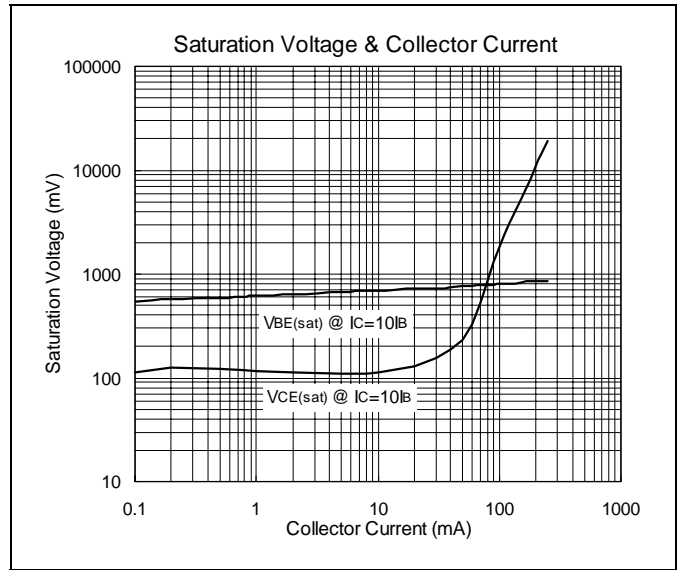
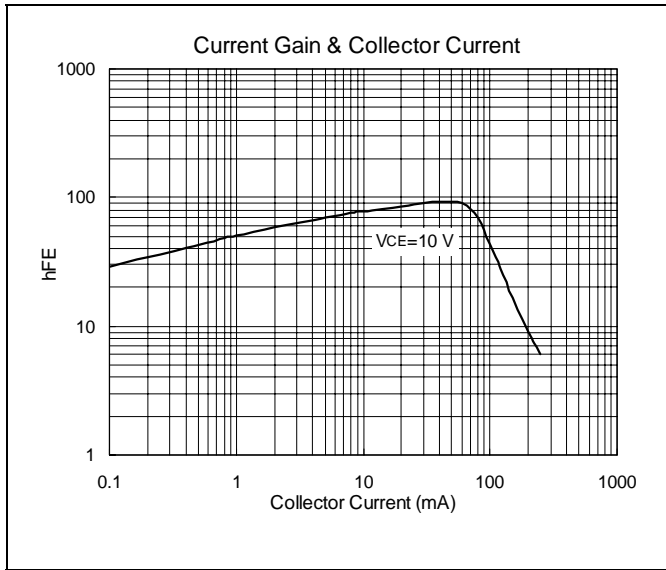
*Pulse Test : Pulse Width ≤380us, Duty Cycles≤2%

Classification Of hFE

Rank	C	D	E	F
Range	40-80	60-120	100-200	160-320

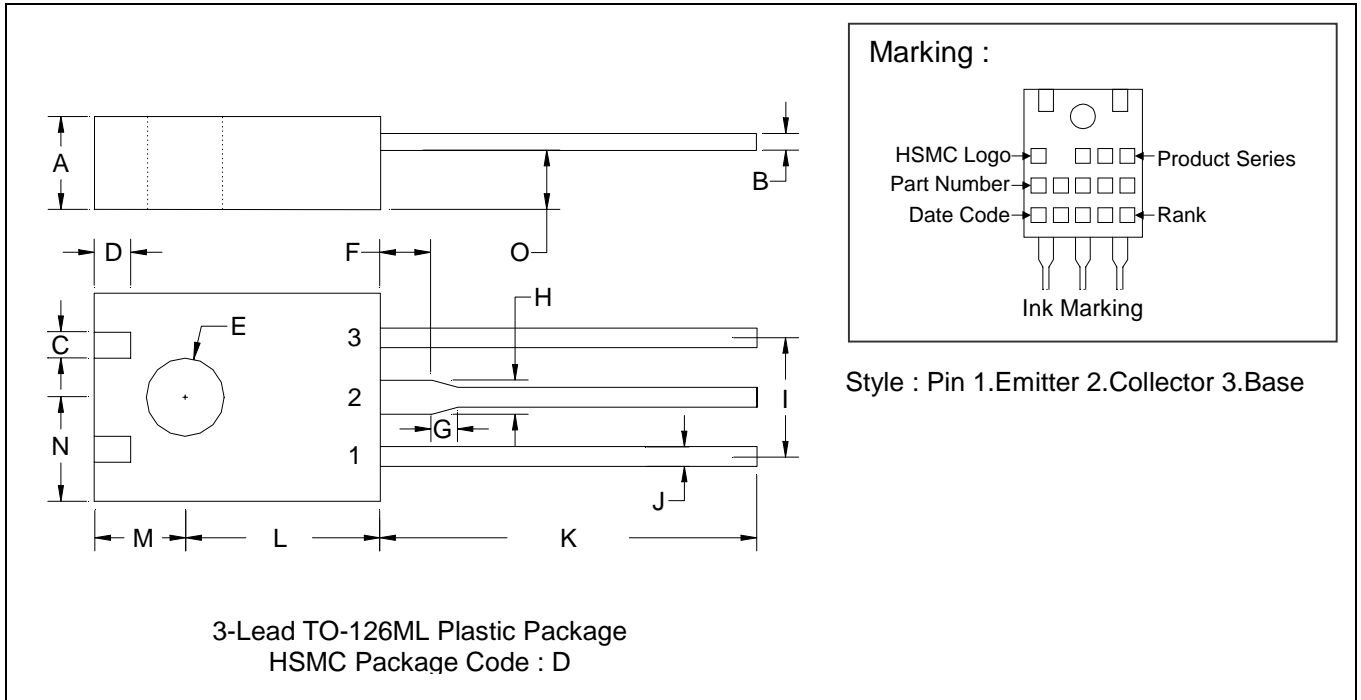


Characteristics Curve

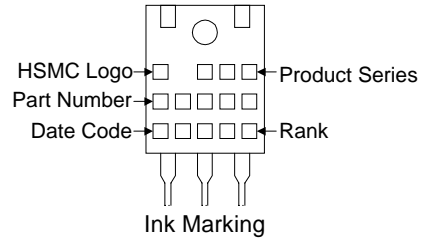




TO-126ML Dimension



Marking :



Style : Pin 1. Emitter 2. Collector 3. Base

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1356	0.1457	3.44	3.70	I	-	*0.1795	-	*4.56
B	0.0170	0.0272	0.43	0.69	J	0.0268	0.0331	0.68	0.84
C	0.0344	0.0444	0.87	1.12	K	0.5512	0.5906	14.00	15.00
D	0.0501	0.0601	1.27	1.52	L	0.2903	0.3003	7.37	7.62
E	0.1131	0.1231	2.87	3.12	M	0.1378	0.1478	3.50	3.75
F	0.0737	0.0837	1.87	2.12	N	0.1525	0.1625	3.87	4.12
G	0.0294	0.0494	0.74	1.25	O	0.0740	0.0842	1.88	2.14
H	0.0462	0.0562	1.17	1.42					

Notes : 1.Dimension and tolerance based on our Spec. dated Mar. 6,1995.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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